



SPECIFICATIONS

xpii+ I CAPABILITY

Tact time	xpii+ I - 0.265 sec - 13,580cph (IPC 11,580cph) xpii+ IT - 0.234 sec - 15,390cph (IPC 12,550cph)
Placement accuracy	35µm (QFPs) to 60µm (chips) @ 3 sigma
Placement head	1 rotary turret head on X/Y linear motor gantry xpii+ I with 8 nozzle positions xpii+ IT with 12 nozzle positions
Nozzles	1 x 40 position 'smart' nozzle tool bank (2 x 40) or (1 x 40 + 1 x 20 + 1 special bank as an option)
Component analysis	'On-the-fly' high resolution digital camera (fixed camera as an option)
Feeder range	Full range of intelligent feeders for 8mm - 104mm tapes, components in plastic sticks and matrix trays
Feeder capacity	92 x 8mm tape feeder positions

xpii+ II CAPABILITY

Tact time	xpii+ II - 0.136 sec - 26,400cph (IPC 20,070cph) xpii+ IIT - 0.12 sec - 30,000cph (IPC 22,380cph)
Placement accuracy	35µm (QFPs) to 60µm (chips) @ 3 sigma
Placement head	2 rotary turret heads on X/Y linear motor gantries xpii+ I with 8 nozzle positions xpii+ IT with 12 nozzle positions
Nozzles	2 x 40 position 'smart' nozzle tool bank (1 x 40 + 1 x 20 + 1 special bank as an option)
Component analysis	'On-the-fly' high resolution digital camera
Feeder range	Full range of intelligent feeders for 8mm to 104mm tapes, components in plastic sticks and matrix trays
Feeder capacity	92 x 8mm tape feeder positions

BOARD HANDLING

Length	60mm to 500mm
Width xpii+ I	60mm to 550mm with 1 nozzle tool bank (front only) (60mm to 515mm with tray sequencer) 60mm to 460mm with 2 nozzle tool banks (front and rear) (60mm to 425mm with tray sequencer)
Width xpii+ II	60mm to 460mm (60mm to 425mm with tray sequencer)
Thickness, Weight	0.5mm to 10.0mm; 3Kg max.
Under board clearance	25mm
Board location	Full edge clamping with fiducial correction
Board edge clearance	3mm above / 5mm below
Transport criteria	Left to right (right to left optional), fixed front rail, height-adjustable 890mm to 975mm, SMEMA interface

COMPONENT RANGE

Types	Chips, MELFs, electrolytic capacitors, SO, PLCC, QFP, TSOP, QFN, BGA, µBGA, LGA, CSP, connectors, Flip chip, through hole and odd-form surface mount devices
Minimum size	0.4mm x 0.2mm (01005)
Maximum size	50mm x 50mm as standard, 70 x 70mm and 100mm long connectors and other devices with fixed camera option
Maximum height	Full revolution of turret 12mm xpii+ I and xpii+ II - 1 component mode 32.5mm xpii+ IT and xpii+ IIT - 1 component mode 31mm
Minimum lead pitch	0.3mm (QFP), 0.4mm (µBGA) 0.15mm (QFP), 0.2mm (µBGA) with optional fixed camera
Minimum lead/ball size	0.15mm (QFP), 0.2mm (µBGA) 0.07mm (QFP), 0.1mm (µBGA) with optional fixed camera

GENERAL

Electric	400V/210V three phase - 50Hz/60Hz - 5 KVA
Air	7 bar, 30 l/min
Noise	<70dB (A)
Working temperature	10°C to 30°C, ideally 20°C +/- 5°C
Humidity	20% to 80% RH non-condensing
Weight xpii+ I	1420Kg (without feeders)
Weight xpii+ II	1500Kg (without feeders)
Colour	RAL9002, RAL5024, RAL7043

SPECIFICATIONS

OPTIONS

Fixed upward looking camera for larger and very fine pitch components (minimum PCB width 100mm, maximum PCB length 490mm)

Internal fixed zone or 30-position automatic loader (sequencer) for matrix trays

Feeder trolley options for bulk change of individual feeders and 'mass' tape feeder ranges

Traceability

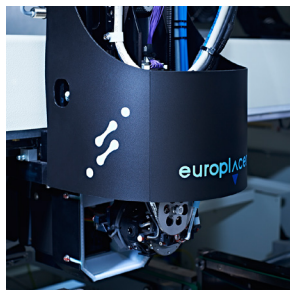
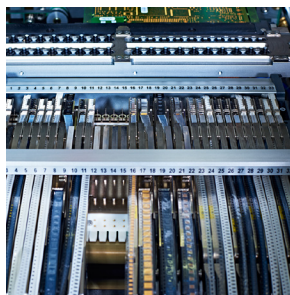
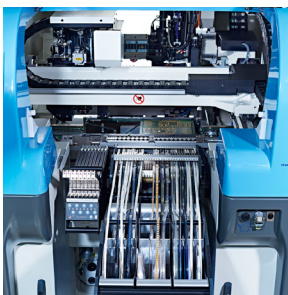
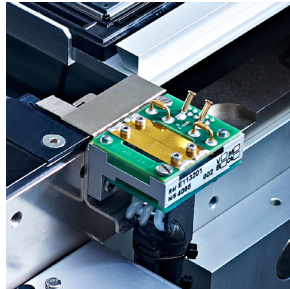
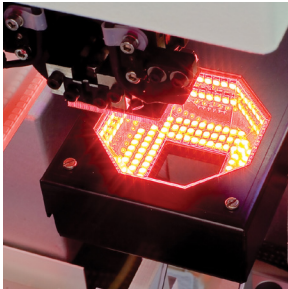
Electrical component testing

Automatic conveyor width adjustment

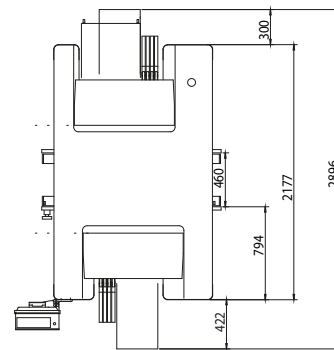
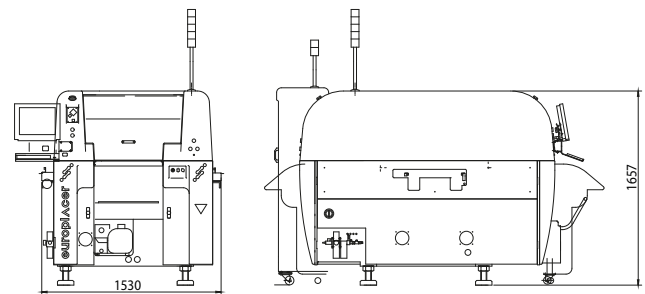
Additional nozzle magazine

Nozzle magazine with 20 positions + special nozzle magazine

Rear operating station



Dimensions in mm.



As part of our policy of continuous development, specifications are subject to change without prior notice.